

SIA445EDJ-T1-GE3-VB Datasheet

P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ.)
- 20	0.020 at $V_{GS} = -10$ V	- 10 ^a	20 nC
	0.028 at $V_{GS} = -4.5$ V	- 8 ^a	
	0.040 at $V_{GS} = -2.5$ V	- 6	

FEATURES

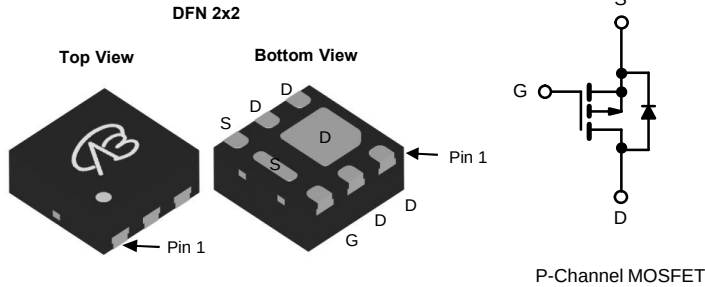
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Portable Devices
 - Load Switch
 - Battery Switch
 - Charger Switch



ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	- 10 ^a	A
		- 7 ^a	
		- 8 ^{b, c}	
		- 7.1 ^{b, c}	
Pulsed Drain Current	I_{DM}	- 30	A
Continuous Source-Drain Diode Current	I_S	- 6 ^a	
		- 2.9 ^{b, c}	
Maximum Power Dissipation	P_D	19	W
		12	
		3.5 ^{b, c}	
		2.2 ^{b, c}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature) ^{d, e}		260	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, e}	R_{thJA}	28	36	$^\circ\text{C/W}$
Maximum Junction-to-Case (Drain)	R_{thJC}	5.3	6.5	

Notes:

a. Package limited.

b. Surface Mounted on 1" x 1" FR4 board.

c. $t = 5$ s.

d. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

e. Maximum under Steady State conditions is 80 $^\circ\text{C/W}$.

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	- 20			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$		- 12		mV/ $^{\circ}\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			3		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$		- 0.6		V
Gate-Source Leakage	I_{GSS}	$V_{DS} = -20\text{ V}, V_{GS} = \pm 12\text{ V}$			± 20	μA
		$V_{DS} = -20\text{ V}, V_{GS} = \pm 4.5\text{ V}$			± 0.5	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$			- 1	
		$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^{\circ}\text{C}$			- 10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \leq -5\text{ V}, V_{GS} = -4.5\text{ V}$	- 20			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -5.6\text{ A}$		0.020		Ω
		$V_{GS} = -4.5\text{ V}, I_D = -5.3\text{ A}$		0.028		
		$V_{GS} = -2.5\text{ V}, I_D = -2.5\text{ A}$		0.040		
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10\text{ V}, I_D = -5.6\text{ A}$		35		S
Dynamic ^b						
Total Gate Charge	Q_g	$V_{DS} = -10\text{ V}, V_{GS} = -8\text{ V}, I_D = -5\text{ A}$		50	75	nC
Gate-Source Charge		$V_{DS} = -10\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -5\text{ A}$		20	30	
	Q_{gs}			3.3		
Gate-Drain Charge	Q_{gd}			8.4		
Gate Resistance	R_g	$f = 1\text{ MHz}$	0.2	1	2	k Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\text{ V}, R_L = 1\text{ }\Omega$ $I_D \cong -5\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$		0.71	1.1	μs
Rise Time	t_r			1.7	2.6	
Turn-Off Delay Time	$t_{d(off)}$			6	9	
Fall Time	t_f			3.2	5	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\text{ V}, R_L = 1\text{ }\Omega$ $I_D \cong -5\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$		0.3	0.45	
Rise Time	t_r			0.6	0.9	
Turn-Off Delay Time	$t_{d(off)}$			10	15	
Fall Time	t_f			3.5	5.5	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^{\circ}\text{C}$			- 10	A
Pulse Diode Forward Current	I_{SM}				- 30	
Body Diode Voltage	V_{SD}	$I_S = -5\text{ A}, V_{GS} = 0\text{ V}$		- 0.85	- 1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 6\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^{\circ}\text{C}$		30	60	ns
Body Diode Reverse Recovery Charge	Q_{rr}			20	40	nC
Reverse Recovery Fall Time	t_a			13		ns
Reverse Recovery Rise Time	t_b			17		

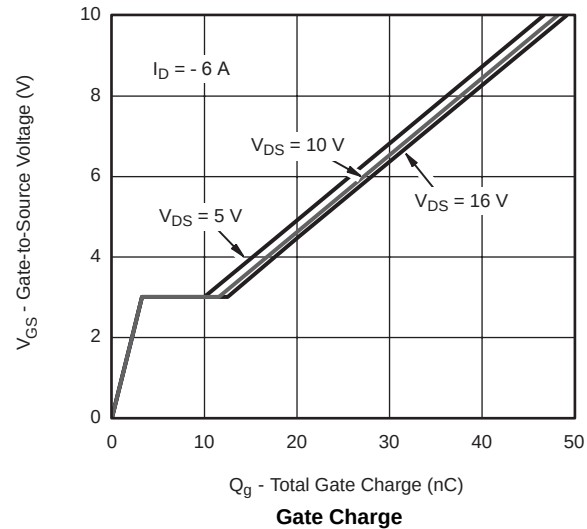
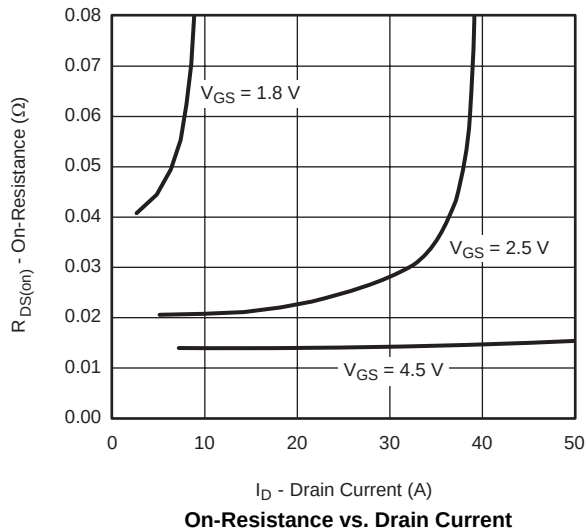
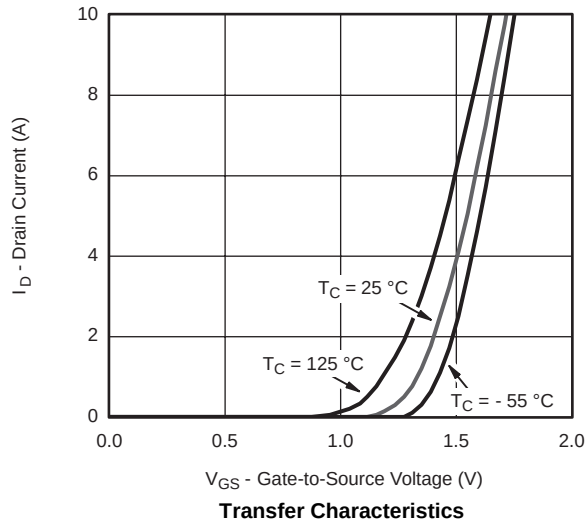
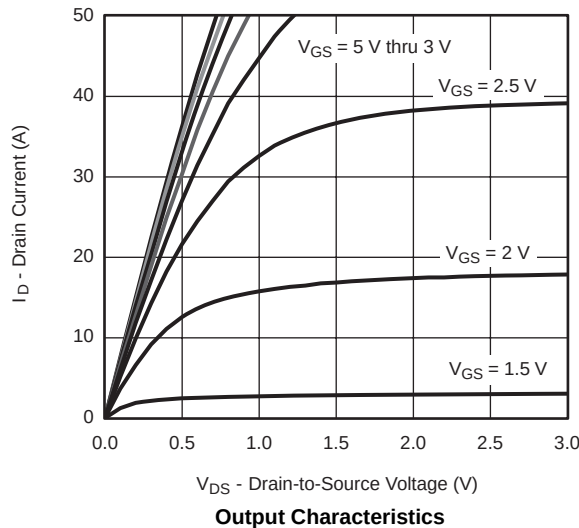
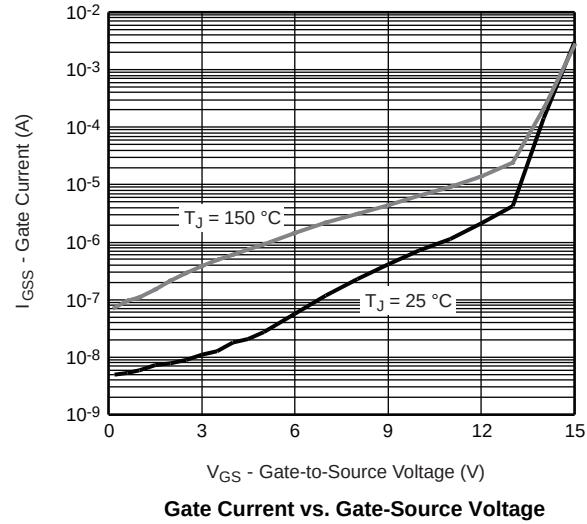
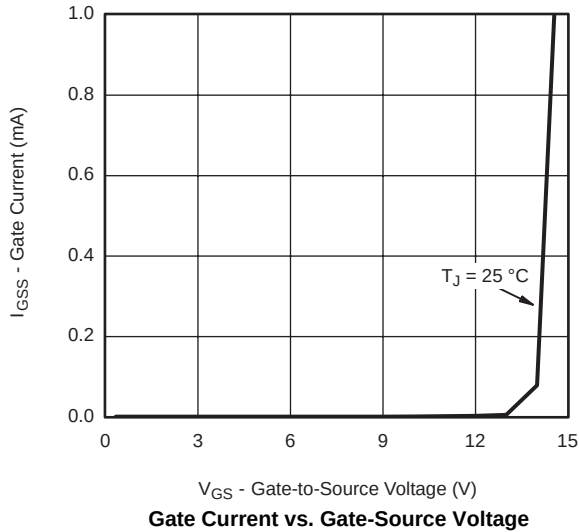
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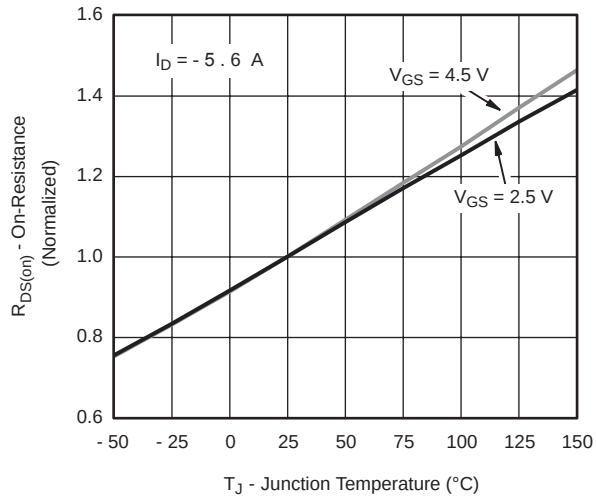
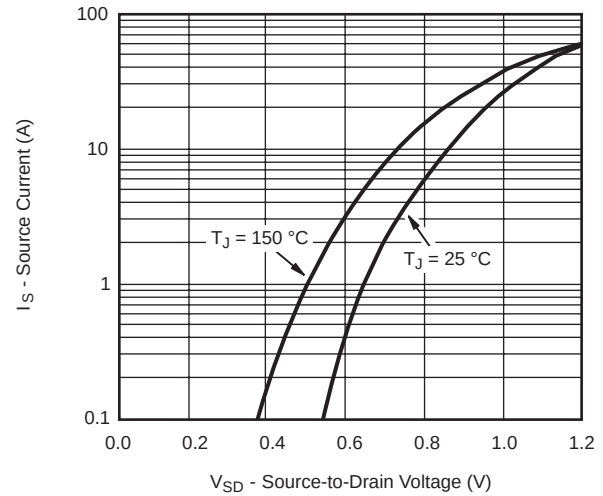
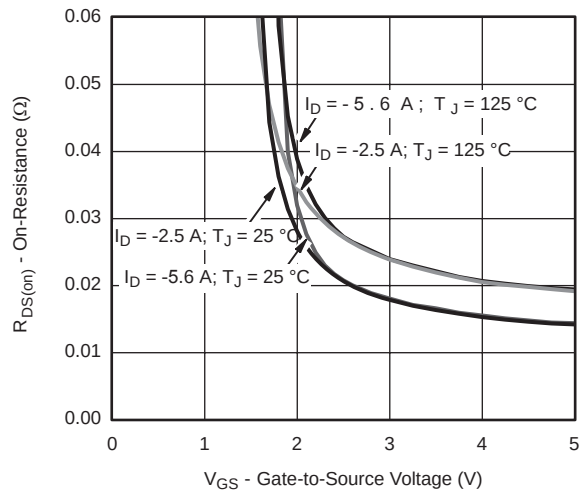
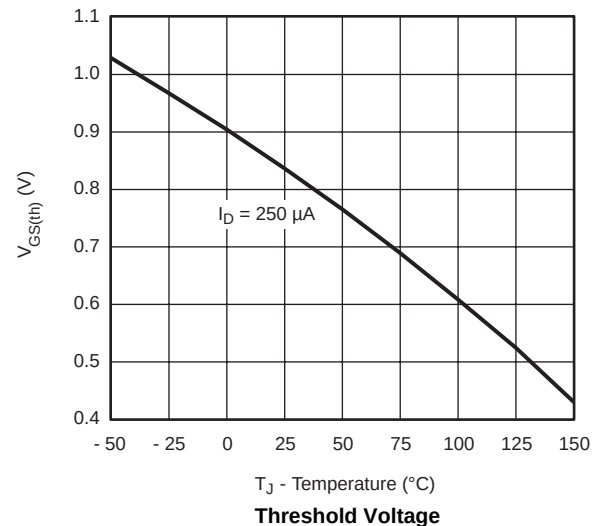
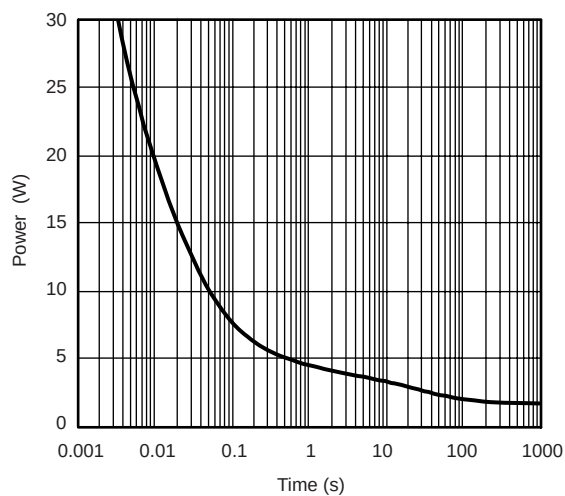
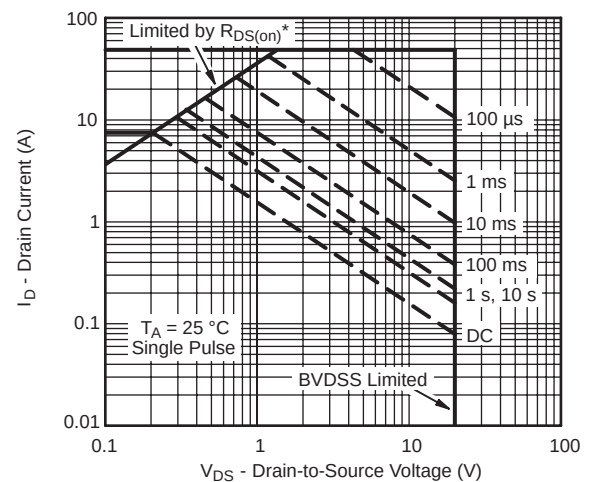
a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

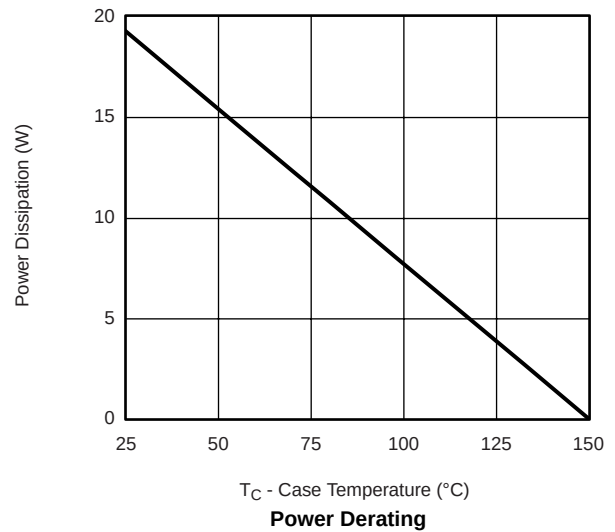
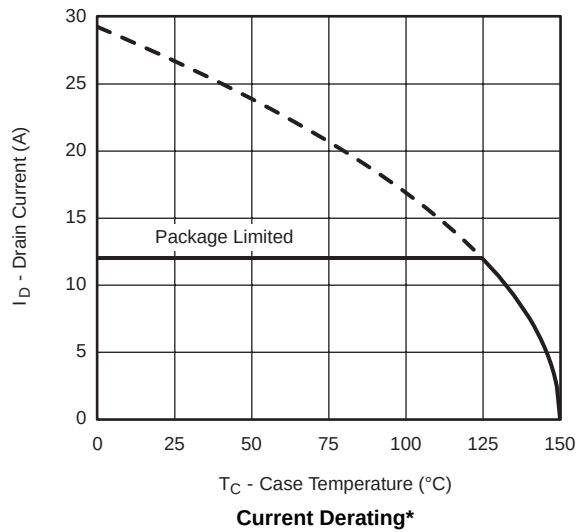
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

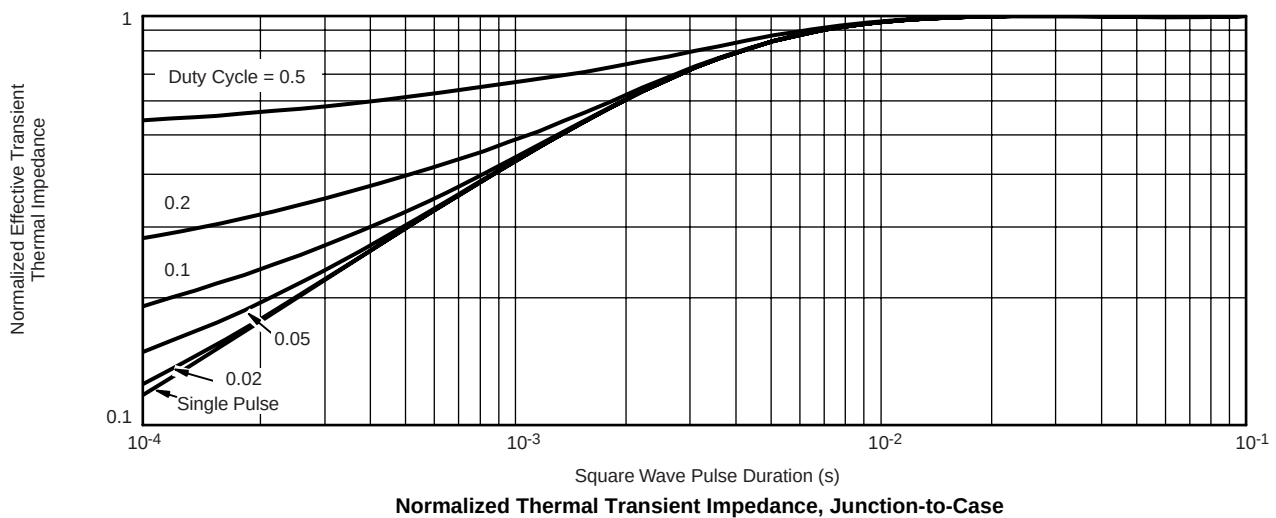
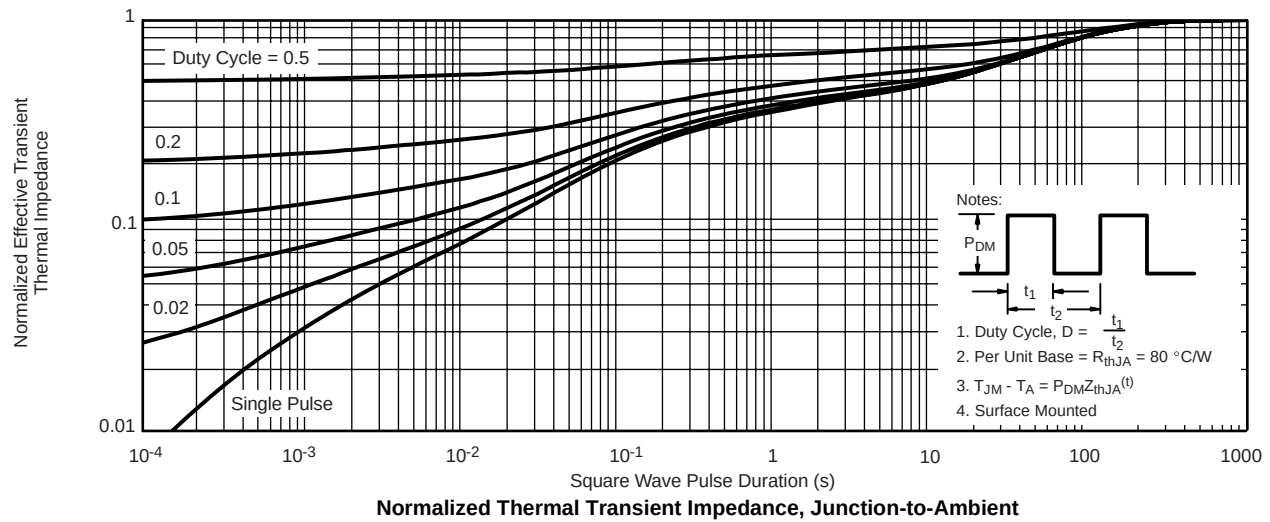
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



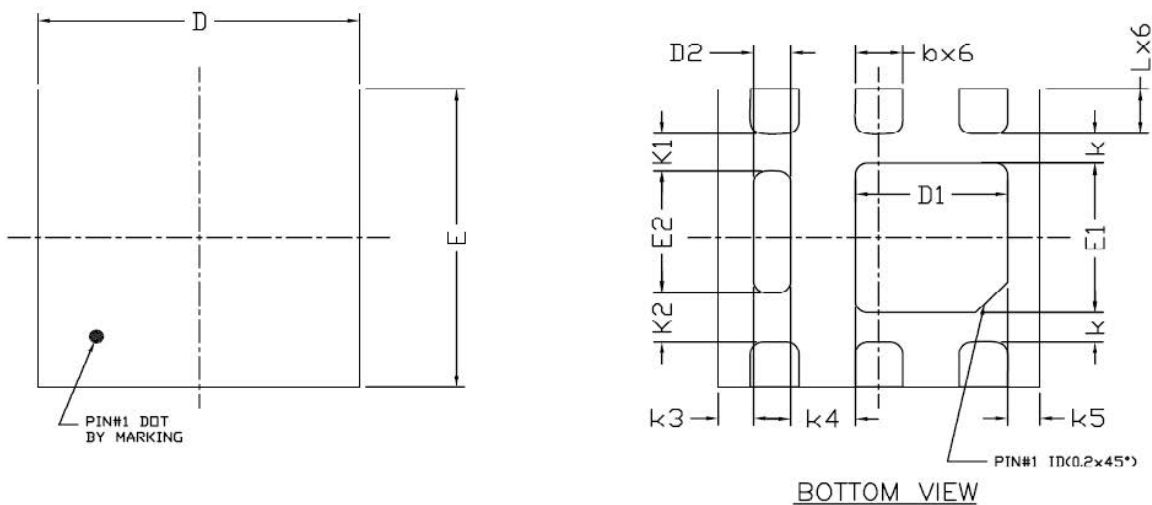
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage

Single Pulse Power, Junction-to-Ambient

Safe Operating Area, Junction-to-Ambient
 * $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

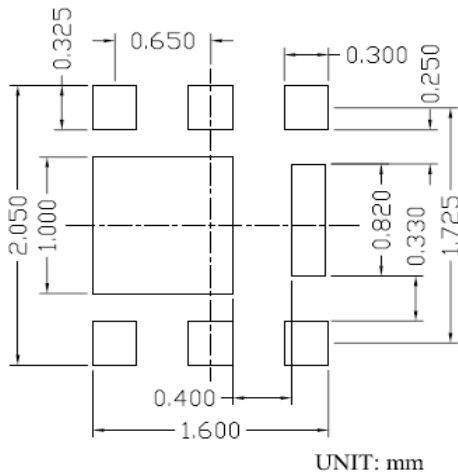
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


DFN2x2 _6L_EP1_S PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



NOTE
1. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
A1	0.00	—	0.05	0.000	—	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.152 REF			0.006 REF		
D	1.90	2.00	2.10	0.075	0.079	0.083
D1	0.85	0.95	1.05	0.033	0.037	0.041
D2	0.13	0.23	0.33	0.005	0.009	0.013
E	1.90	2.00	2.10	0.075	0.079	0.083
E1	0.90	1.00	1.10	0.035	0.039	0.043
E2	0.72	0.82	0.92	0.028	0.032	0.036
e	0.65 BSC			0.026 BSC		
K	0.20 BSC			0.008 BSC		
K1	0.25 BSC			0.010 BSC		
K2	0.33 BSC			0.013 BSC		
K3	0.22 BSC			0.009 BSC		
K4	0.40 BSC			0.016 BSC		
K5	0.20 BSC			0.008 BSC		
L	0.25	0.30	0.35	0.010	0.012	0.014

Figure 1 is a technical drawing of a mechanical part, labeled '1'. The drawing shows the front and side views of the part, with dimensions in millimeters (mm) and inches (in) provided for each feature.

Front View Dimensions:

- Overall width: 9.50 (0.37)
- Overall height: 2.200 (0.087)
- Top flange width: 0.300 (0.012)
- Top flange height: 0.350 (0.014)
- Central body width: 0.650 (0.026)
- Central body height: 1.500 (0.059)
- Bottom flange width: 0.650 (0.026)
- Bottom flange height: 0.350 (0.014)

Side View Dimensions:

- Overall width: 0.650 (0.026)
- Overall height: 0.870 (0.034)
- Top flange width: 0.300 (0.012)
- Top flange height: 0.350 (0.014)
- Central body width: 0.550 (0.022)
- Central body height: 0.475 (0.019)
- Bottom flange width: 0.300 (0.012)
- Bottom flange height: 0.355 (0.014)

Feature Details:

- The central body has a large rectangular hole with a width of 0.650 (0.026) and a height of 1.500 (0.059).
- The top flange has a central hole with a diameter of 0.300 (0.012).
- The bottom flange has a central hole with a diameter of 0.300 (0.012).
- The side view shows a central hole with a diameter of 0.550 (0.022) and a height of 0.475 (0.019).

Dimensions in mm/(Inches)

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